

PEREGRINE MATERIAL DECLARATION FORM

Product:	PE42521
Ordering Codes:	PE42521C-Z
Description:	UltraCMOS SPDT RF Switch 9 kHz - 13 GHz
Package:	16L 3x3 QFN
Environmental Compliance	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
SOI Wafer	Aluminum oxide	1344-28-1	1.296147	5.58%	55,826.54
SOI Wafer	Aluminum	7429-90-5	0.003943	0.02%	169.81
SOI Wafer	Silicon	7440-21-3	0.000263	0.00%	11.32
SOI Wafer	Arsenic	7440-38-2	0.000001	0.00%	0.06
SOI Wafer	Boron	7440-42-8	0.000001	0.00%	0.06
SOI Wafer	Phosphorus	7723-14-0	0.000005	0.00%	0.23
SOI Wafer	Titanium	7440-32-6	0.000657	0.00%	28.30
SOI Wafer	Tungsten	7440-33-7	0.013142	0.06%	566.04
SOI Wafer	Cobalt	7440-48-4	0.000026	0.00%	1.13
SOI Wafer	Copper	7440-50-8	0.000011	0.00%	0.45
Leadframe	Copper	7440-50-8	9.054500	39.00%	389,987.75
Leadframe	Chromium	7440-47-3	0.022800	0.10%	982.02
Leadframe	Tin	7440-31-5	0.022800	0.10%	982.02
Leadframe	Zinc	7440-66-6	0.020100	0.09%	865.73
Die Attach	Silver	7440-22-4	0.135200	0.58%	5,823.22
Die Attach	2-Butoxyethyl Acetate	112-07-2	0.015200	0.07%	654.68
Die Attach	2-Propenoic acid, 3-(trimethoxysilyl)propy	4369-14-6	0.001500	0.01%	64.61
Wire	Gold	7440-57-5	0.160600	0.69%	6,917.23
Plating	Nickel	7440-02-0	0.066600	0.29%	2,868.54
Plating	Palladium	5/3/7440	0.005400	0.02%	232.58
Plating	Gold	7440-57-5	0.000200	0.00%	8.61
Mold Compound	Silica Fused	60676-86-0	11.369300	48.97%	489,688.85
Mold Compound	Epoxy Resin	Trade secret	0.495900	2.14%	21,358.98
Mold Compound	Phenol Resin	Trade secret	0.495900	2.14%	21,358.98
Mold Compound	Carbon Black	1333-86-4	0.037200	0.16%	1,602.25
Total Weight (mg)			23.217396	100.00%	1,000,000